

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-8 (Canceled)

9. (Currently Amended) A semiconductor device test probe having a tip portion for being urged against a plurality of electrode pads of an integrated semiconductor device to establish electrical contacts between the tip portion and the electrode pads for testing an operation of the semiconductor;

 said test probe having a side surface portion and a tip portion, said tip portion defining a spherical surface and said spherical surface having a radius of curvature r expressed by $10 \mu\text{m} \leq r \leq 20 \mu\text{m}$, and said tip portion having a surface roughness equal to or less than $0.4 \mu\text{m}$.

10. (Currently Amended): A semiconductor device test probe having a tip portion for being urged against a plurality of electrode pads of an integrated semiconductor device to establish electrical contacts between the tip portion and the electrode pads for testing an operation of the semiconductor;

 said test probe having a side surface portion and a tip portion, said tip portion defining a spherical surface and said spherical surface having a radius of curvature r expressed by $10 \mu\text{m} \leq r \leq 20 \mu\text{m}$, and said tip portion generating a shear deformation on the electrode pads, and said tip portion having a surface roughness equal to or less than $0.4 \mu\text{m}$.

11. (New): A probe card having a plurality of probes which can be brought into contact with a plurality of electrode pads to test the semiconductor device, wherein the card comprises the probe of claim 1.

12. (New): A probe card having a plurality of probes which can be brought into contact with a plurality of electrode pads to test the semiconductor device, wherein the card comprises the probe of claim 2.